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PRE-RELEASE VERSION (FDIS)

Integrated circuits – EMC evaluation of transceivers – Part 7: CXPI transceivers

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FINAL DRAFT INTERNATIONAL STANDARD (FDIS)

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SECRETARIAT: Japan	SECRETARY: Mr Yoshinori FUKUBA
OF INTEREST TO THE FOLLOWING COMMITTEES:	HORIZONTAL STANDARD: ☐
FUNCTIONS CONCERNED: ☒ EMC ☐ ENVIRONMENT	☒ QUALITY ASSURANCE ☐ SAFETY
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TITLE:

Integrated circuits - EMC evaluation of transceivers – Part 7: CXPI transceivers

PROPOSED STABILITY DATE: 2027

NOTE FROM TC/SC OFFICERS:

The comments for CDV have been reviewed and filed the observations at working group 9 meeting on 2021-10-05 and SC47A has decided next step to be FDIS. The decision and observations are indicated in 47A/1128/RVC.

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INTEGRATED CIRCUITS – EMC EVALUATION OF TRANSCEIVERS –

Part 7: CXPI transceivers

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IEC 62228-7 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47A/XX/FDIS	47A/XX/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 62228 series, published under the general title *Integrated circuits – EMC evaluation of transceivers*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTEGRATED CIRCUITS – EMC EVALUATION OF TRANSCEIVERS –

Part 7: CXPI transceivers

1 Scope

This part of IEC 62228 specifies test and measurement methods for the EMC evaluation of CXPI transceiver ICs under network condition. It defines test configurations, test conditions, test signals, failure criteria, test procedures, test setups and test boards. This specification is applicable for standard CXPI transceiver ICs and ICs with embedded CXPI transceiver and covers

- the emission of RF disturbances,
- the immunity against RF disturbances,
- the immunity against impulses and
- the immunity against electrostatic discharges (ESD).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61967-1, *Integrated circuits – Measurement of electromagnetic emissions – Part 1: General conditions and definitions*

IEC 61967-4, *Integrated circuits – Measurement of electromagnetic emissions – Part 4: Measurement of conducted emissions – 1 Ω/150 Ω direct coupling method*

IEC 62132-1, *Integrated circuits – Measurement of electromagnetic immunity – Part 1: General conditions and definitions*

IEC 62132-4:2006, *Integrated circuits – Measurement of electromagnetic immunity 150 kHz to 1 GHz – Part 4: Direct RF power injection method*

IEC 62215-3, *Integrated circuits – Measurement of impulse immunity – Part 3: Non-synchronous transient injection method*

IEC 62228-1, *Integrated circuits – EMC evaluation of transceivers – Part 1: General conditions and definitions*

ISO 7637-2, *Road vehicles – Electrical disturbances from conduction and coupling – Part 2: Electrical transient conduction along supply lines only*

ISO 10605, *Road vehicles – Test methods for electrical disturbances from electrostatic discharge*

ISO 20794-4, *Road vehicles – Clock extension peripheral interface (CXPI) – Part 4: Data link layer and physical layer*

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ISO 20794-7:2020, *Road vehicles – Clock extension peripheral interface (CXPI) – Part 7: Data link and physical layer conformance test plan*